

JSR ELPAC™ WPR™ / FG series Photo-Imageable Dielectric (PID)

WPR/FG Series

Common Features

High Resolution
Low shrinkage
Good adhesion

FT = 1 ~ 5 μm

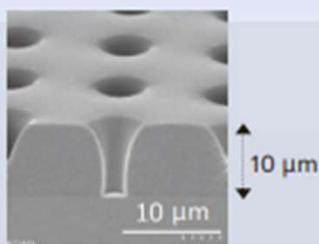


0.5 μm -Space 2 μm -SQ

FG (Positive-tone)

- ✓ Low Dk: 2.9
- ✓ Low cure shrinkage: 5%
- ✓ h-line DI

FT = 1 ~ 15 μm

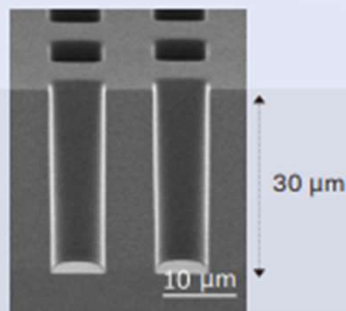


2 μm -SQ

WPR (Positive-tone)

- ✓ High Tg: 345 °C
- ✓ h-line DI

FT = 15 ~ 60 μm



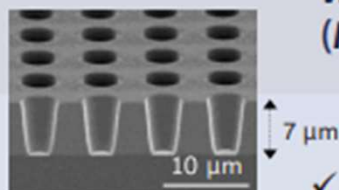
7 μm -SQ

WPR (Negative-tone)

- ✓ Gap-filling
- ✓ CMP and Hybrid bonding

PFAS Free Samples Available

FT = 5 ~ 10 μm

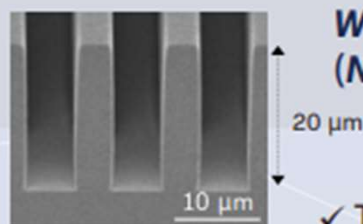


2.5 μm -SQ

WPR (Positive-tone)

- ✓ Excellent Adhesion

FT = 10 ~ 20 μm

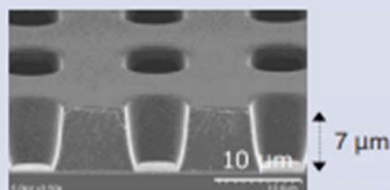


5 μm -L/S

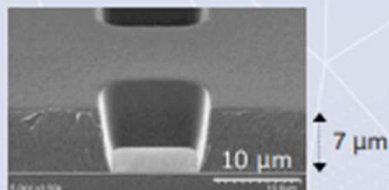
WPR (Negative-tone)

- ✓ Thick film

PI Series (PFAS Free) -under development



5 μm -SQ



10 μm -SQ

Polyimide (Positive-tone)

- ✓ Good elongation: >60%
- ✓ High Tg: 330 °C
- ✓ Low CTE: 45 ppm/°C